

High Power GaAs SPDT Switch DC - 2.0 GHz

Rev. V6

Features

- Positive Supply and Control Voltages
- 1 dB Compression Point: +36 dBm Typical, 8 V
- 3rd Order Intercept Point: +65 dBm Typical, 8 V
- Low Insertion Loss: 0.4 dB Typical
- Low Power Consumption: 100 μ W
- Fast Switching Speed

Description

M/A-COM's SW-277 is a GaAs MMIC SPDT switch in a SOIC-8 lead surface mount plastic package. The SW-277 is ideally suited for use where low power consumption is required.

Typical applications include transmit/receive switching, switch matrices and switched filter banks in systems such as radio and cellular equipment, PCM, GPS, fiber optic modules, and other battery powered radio equipment.

The SW-277 is fabricated using a monolithic GaAs MMIC using a mature 1 micron process. The process features full chip passivation for increased performance and reliability.

Ordering Information¹

Part Number	Package
SW-277	Bulk Packaging
SW-277TR	1000 piece reel

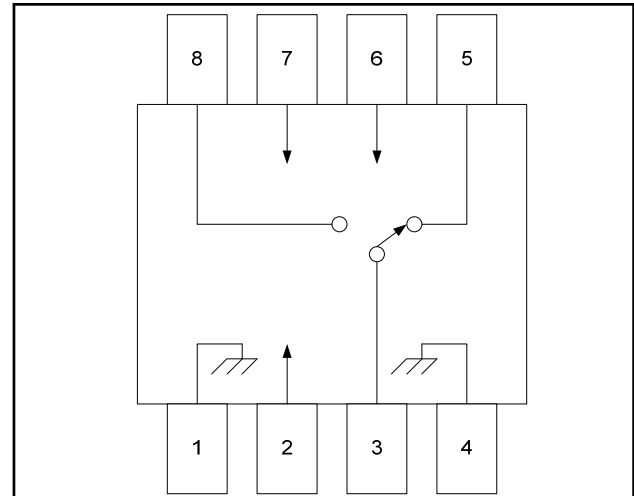
1. Reference Application Note M513 for reel size information.

Truth Table²

Control Inputs		Condition of Switch RF Common to Each RF Port	
A	B	RF1	RF2
1	0	Off	On
0	1	On	Off

2. "0" = 0 to +0.2 V @ 20 μ A maximum.
"1" = +5 V @ 20 μ A typical to 10 V @ 500 μ A maximum.

Functional Schematic



Pin Configuration

Pin No.	Description	Pin No.	Description
1	Ground, Thermal Contact	5	RF Port 1 ³
2	V _{DD}	6	Control A
3	RFC ³	7	Control B
4	Ground, Thermal Contact	8	RF Port 2 ³

3. External DC blocking capacitors required on all RF ports.

Absolute Maximum Ratings^{4,5}

Parameter	Absolute Maximum
Input Power - 0.5 - 2.0 GHz 5 V Control and Supply 8 V Control and Supply 10 V Control and Supply	+37 dBm +40 dBm +42 dBm
Power Dissipation	1.0 W
Supply Voltage	-1 V \leq V _{DD} \leq +12 V
Control Voltage	-1 V \leq V _C \leq V _{DD} + 0.2 V
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C
Thermal Resistance ⁶	θ_{jc} = 87°C/W

4. Exceeding any one or combination of these limits may cause permanent damage to this device.
5. M/A-COM does not recommend sustained operation near these survivability limits.
6. Thermal resistance is given for T_A = 25°C. T_{CASE} is the temperature of leads 1 and 4.

1

ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.

PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

- **North America** Tel: 800.366.2266 / Fax: 978.366.2266
 - **Europe** Tel: 44.1908.574.200 / Fax: 44.1908.574.300
 - **Asia/Pacific** Tel: 81.44.844.8296 / Fax: 81.44.844.8298
- Visit www.macomtech.com for additional data sheets and product information.

M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

High Power GaAs SPDT Switch DC - 2.0 GHz

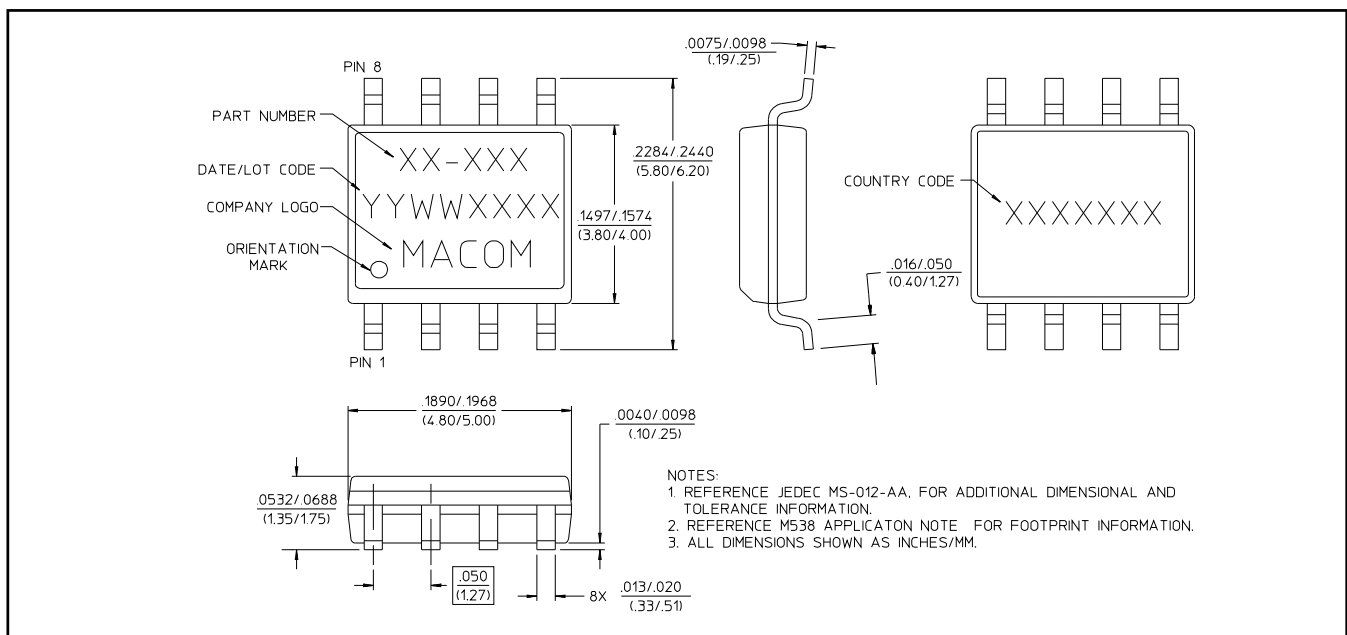
Rev. V6

Electrical Specifications⁷: $T_A = +25^\circ\text{C}$, $V_{DD} = +5\text{ V}$, $V_C = +5\text{ V} / 0\text{ V}$, $P_{IN} = +30\text{ dBm}$

Parameter	Test Conditions	Units	Min.	Typ. ⁸	Max.
Insertion Loss	DC - 0.5 GHz	dB	—	0.45	—
	0.5 - 1.0 GHz	dB	—	0.55	0.65
	1.0 - 2.0 GHz	dB	—	0.6	—
Isolation	DC - 0.5 GHz	dB	—	30	—
	0.5 - 1.0 GHz	dB	27	32	—
	1.0 - 2.0 GHz	dB	—	27	—
VSWR	DC - 2.0 GHz	Ratio	—	1.2:1	—
1 dB Compression	Input Power (5 V Supply/Control) 0.9 GHz	dBm	—	33	—
	Input Power (8 V Supply/Control) 0.9 GHz	dBm	—	35.8	—
Trise, Tfall	10% to 90% RF, 90% to 10% RF	nS	—	30	—
Ton, Toff	50% Control to 90% RF, 50% Control to 10% RF	nS	—	35	—
Transients	In-Band	mV	—	12	—
3rd Order Intercept	Measured Relative to Input Power, two-tone up to +10 dBm (5 V Supply/Control) 0.9 GHz (8 V Supply/Control) 0.9 GHz	dBm	—	55	—
		dBm	—	65	—
Control Current	$V_C = +5\text{ V}$	μA	—	—	20
Supply Current	$V_{DD} = +5\text{ V}$	μA	—	—	60

- All specifications apply when operated with control voltages of 0 V for V_C low and 5 to 10 V for V_C high, and $50\ \Omega$ impedance at all RF ports, unless otherwise specified. High power (greater than 1 W) handling specifications apply to cold switching only. For input powers under 1 W, hot switching can be used. The high control voltage must be within $\pm 0.2\text{ V}$ of the supply voltage. External DC blocking capacitors are required on all RF ports.
- Typical values listed for middle of frequency range noted.

SOIC-8



2

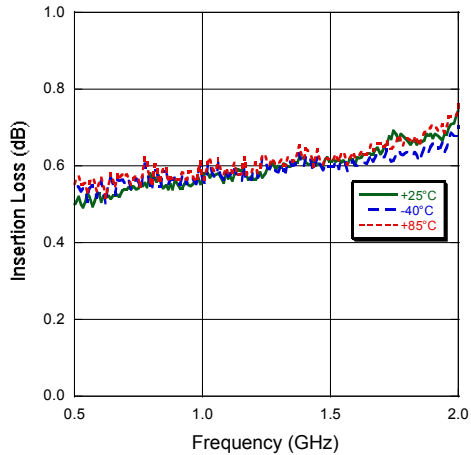
ADVANCED: Data Sheets contain information regarding a product M/A-COM Technology Solutions is considering for development. Performance is based on target specifications, simulated results, and/or prototype measurements. Commitment to develop is not guaranteed.
PRELIMINARY: Data Sheets contain information regarding a product M/A-COM Technology Solutions has under development. Performance is based on engineering tests. Specifications are typical. Mechanical outline has been fixed. Engineering samples and/or test data may be available. Commitment to produce in volume is not guaranteed.

- North America** Tel: 800.366.2266 / Fax: 978.366.2266
 - Europe** Tel: 44.1908.574.200 / Fax: 44.1908.574.300
 - Asia/Pacific** Tel: 81.44.844.8296 / Fax: 81.44.844.8298
- Visit www.macontech.com for additional data sheets and product information.

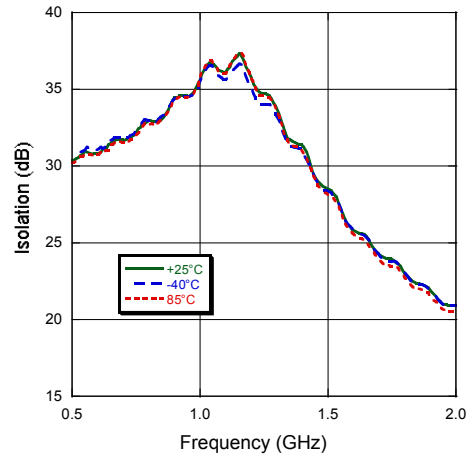
M/A-COM Technology Solutions Inc. and its affiliates reserve the right to make changes to the product(s) or information contained herein without notice.

Typical Performance Curves

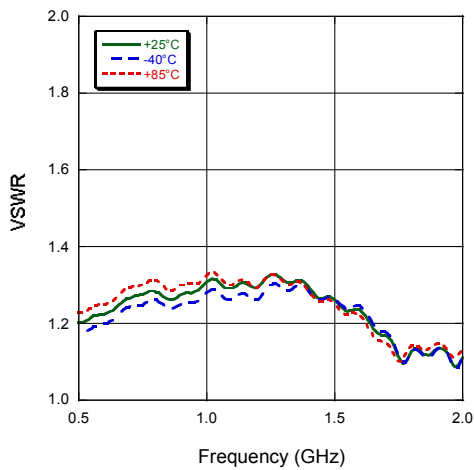
Insertion Loss



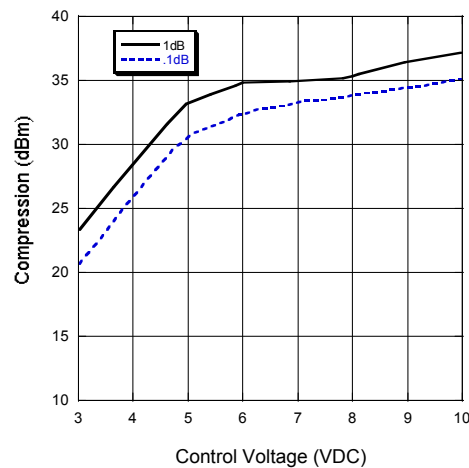
Isolation



VSWR



Compression vs. Control Voltage @ 900 MHz



Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.